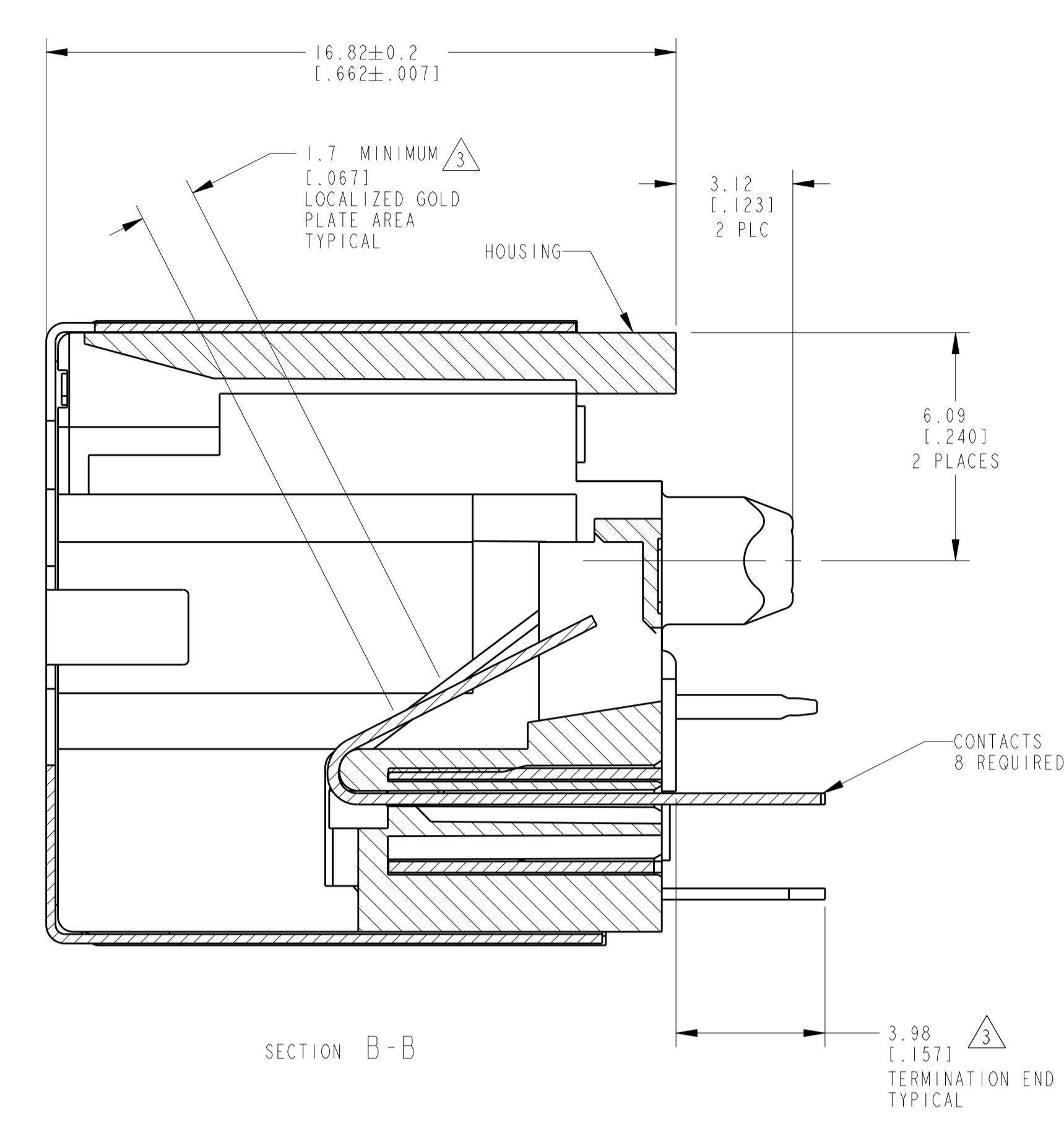
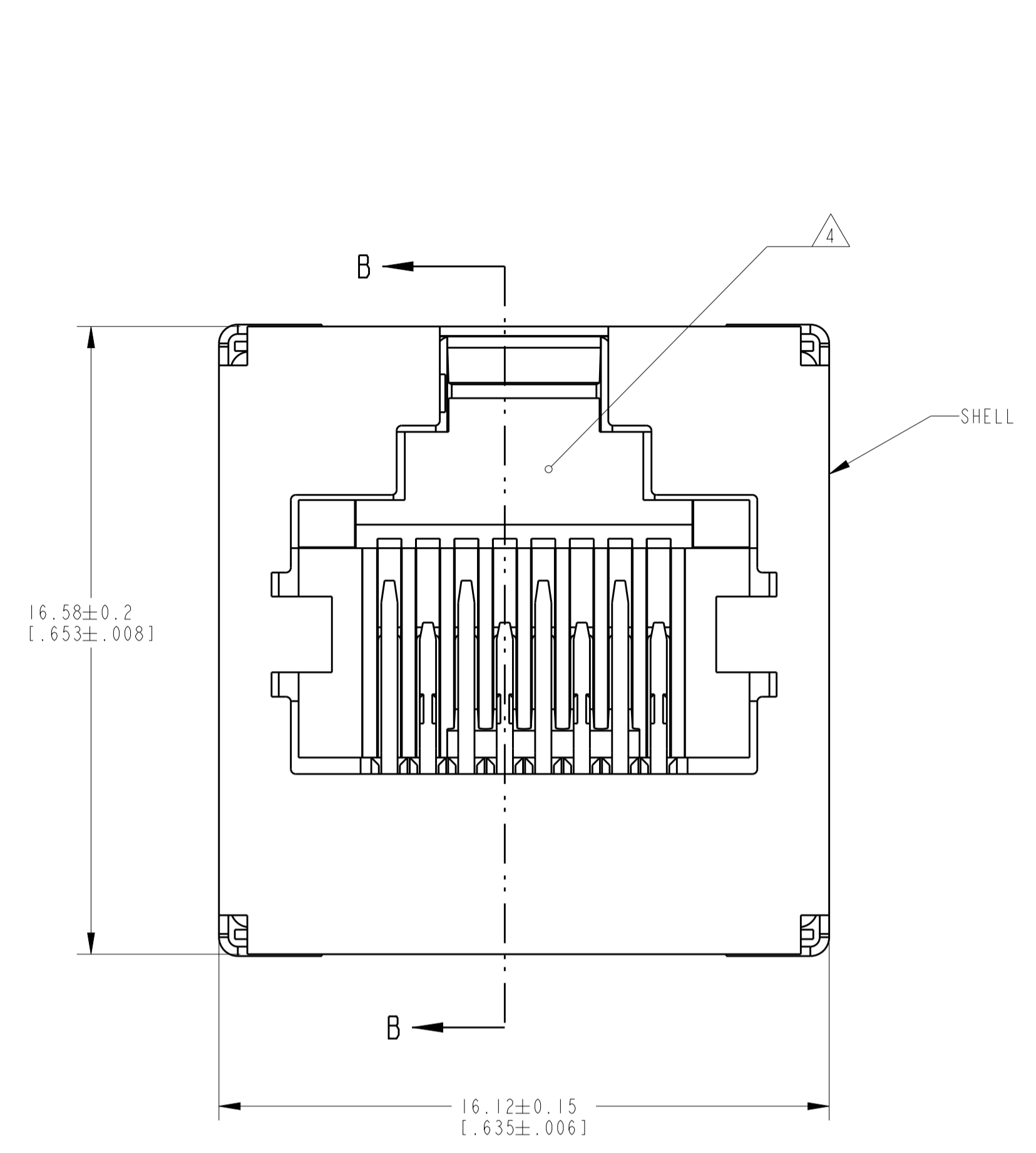
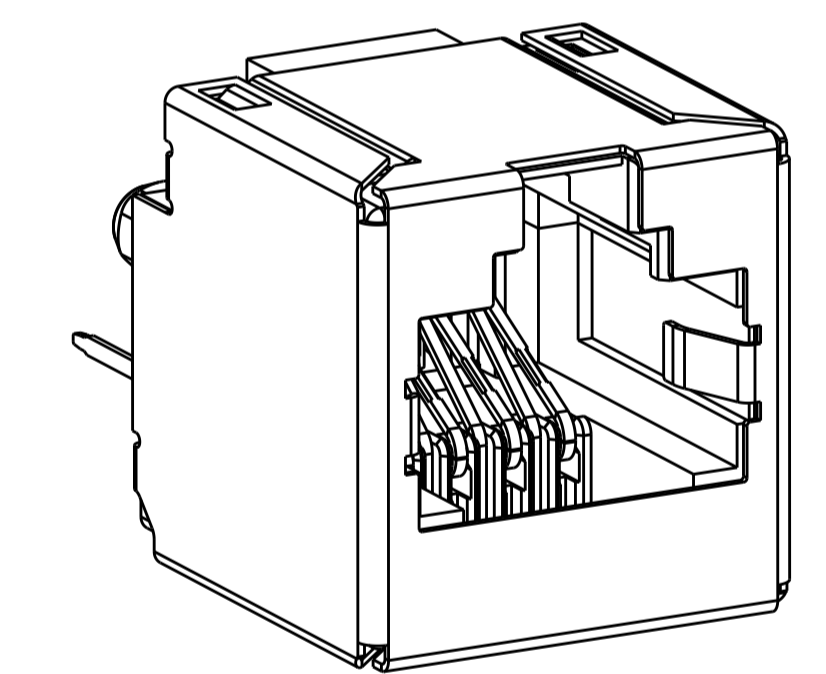
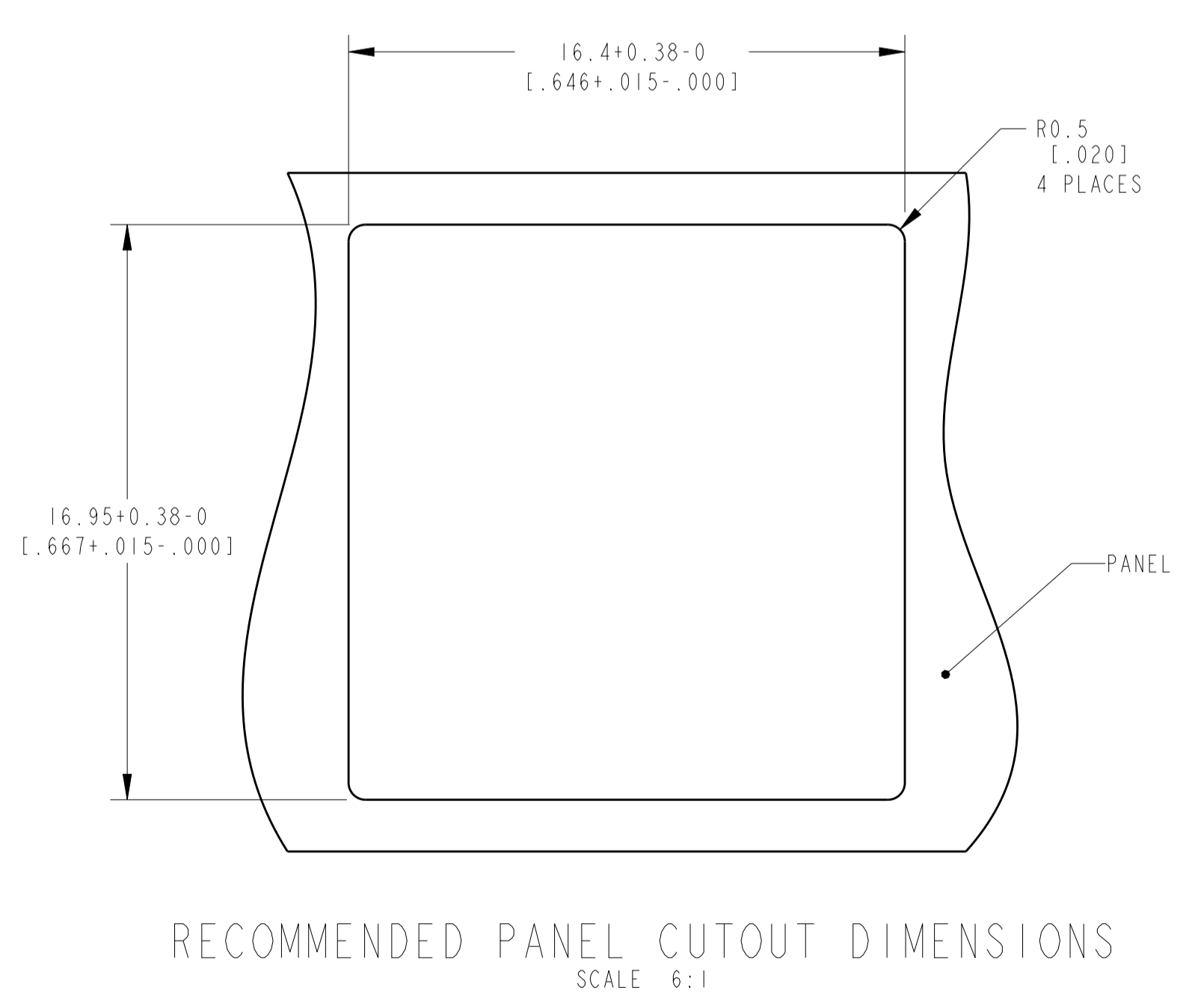
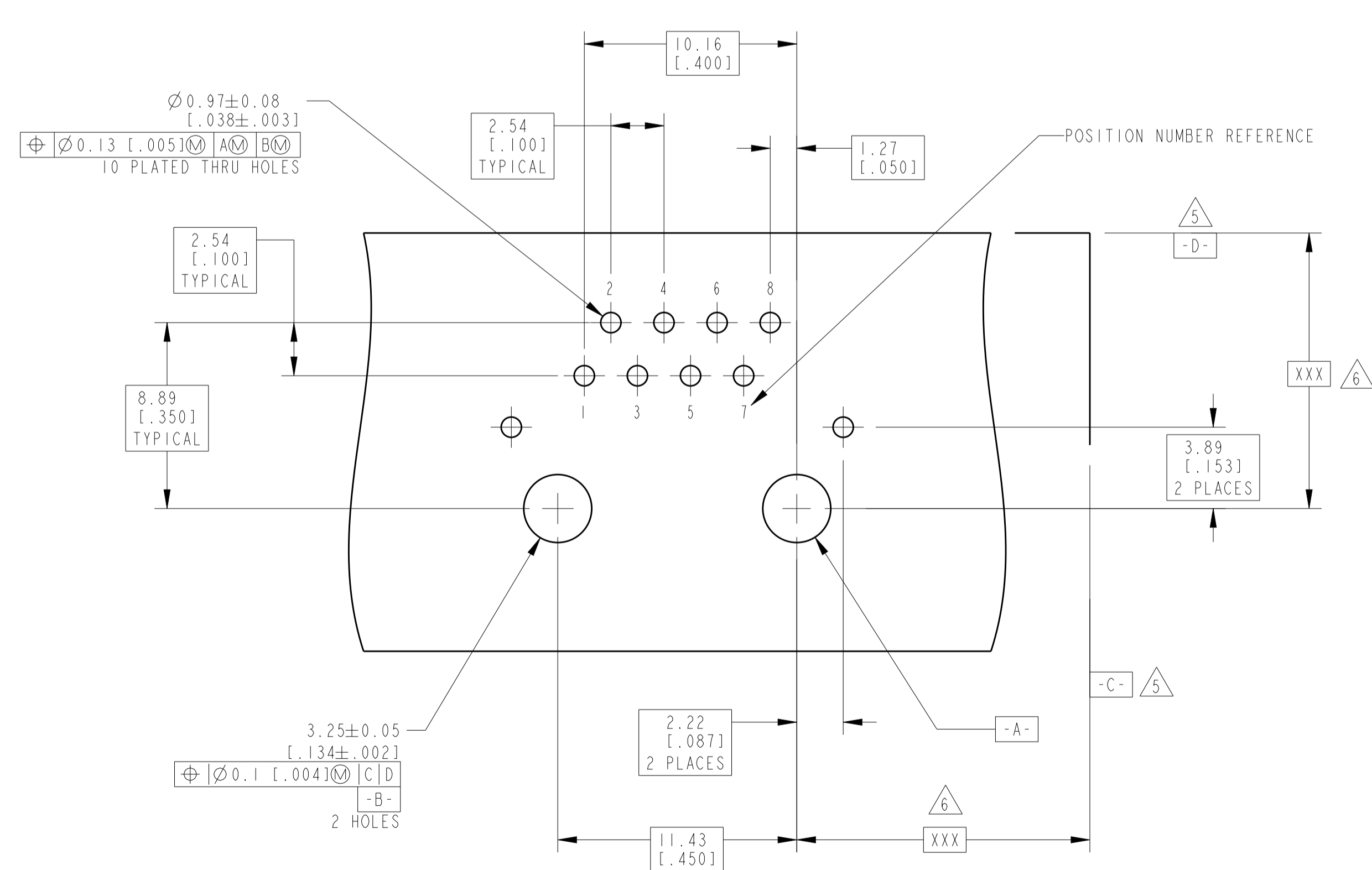


LOC	DIST	REVISIONS					
		P	LTN	DESCRIPTION	DATE	DWN	APVD
AA	22	C1		ECR-12-006114	11APR2012	JJ	AC
		D		ECO-17-018697	15JAN2018	LL	SH
		E		ECO-18-005131	04APR2018	LL	SH



- 1 THERMOPLASTIC, COLOR-BLACK
- 2 PHOSPHOR BRONZE
- 3 1.27µm(.000050) MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2µm(.000079) MIN MATTE TIN ON TERMINATION END, BOTH OVER 1.27µm(.000050) MIN NICKEL
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F
- 5 DATUMS ESTABLISHED BY CUSTOMER
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER
- 7 COPPER ZINC ALLOY
- 8 2.03µm(.000080) MIN BRIGHT TIN OVER 1.27µm(.000050) MIN NICKEL
- 9 WITH IMPROVED CHAFMERS ON TERMINAL EDGES.
- 10 WITHOUT COMPENSATORY PLATE
- 11 LOOSE PIECE PN
- 12 1.27µm(.000050) MIN NICKEL PLATED OVERALL AND 2.03µm(.000080) MIN THICK HOT DIP TIN ON PCB GROUND TABS.
- 13 IR REFLOW PROCESS COMPATIBLE.
- 14 PACKED WITH TAPE/REEL.



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
 RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS 1.4 [0.055] MIN
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD

SHELL PLATING	DESCRIPTION	COLOR	PART NUMBER
2, 9, 13, 14	BLACK	BLACK	6368150-5
8, 9, 10, 11	NATURAL	NATURAL	6368150-4
8, 9, 10	NATURAL	NATURAL	6368150-3
8, 9	NATURAL	NATURAL	6368150-2
8	NORMAL	BLACK	6368150-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWN: 13 JUNE 2005
 CH: V. SLACK/L. A. MATER
 J. WESTMAN
 S. FLICKINGER

TE Connectivity
STE
 MODULAR JACK ASSEMBLY, VERTICAL, THRU HOLE, SHIELDED, 8 POSITION

PRODUCT SPEC: 108-1163-6
 APPLICATION SPEC: 114-2158
 WEIGHT: -
 CUSTOMER DRAWING

SCALE 5:1 SHEET 1 OF 1 REV E

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)